

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1357454	semiconduct\$3 or silicon	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/06/26 15:58
L2	2148858	die or chip\$1 or ((integrated adj circuit) or IC) or (1 adj device\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/06/26 15:59
L3	160728	(heat\$3 or thermal\$2) near2 (sink\$1 or spread\$3 or dissipat\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/06/26 16:01
L4	1322025	diamond\$1 or carbon	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/06/26 16:01
L5	3004	3 with 4	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/06/26 16:01
L6	701	5 same 2	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/06/26 16:01
L7	589	6 and 1	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/06/26 16:02
L8	11641	4 with (cvd or (chemical\$2 adj2 deposit\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/06/26 16:03
L9	231	7 and 8	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/06/26 16:03